

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	25244	(semiconductor or die or chip or IC) and (adhesive or under near fill\$3) and lead	USPAT	2004/02/19 15:13
2	BRS	196378	((semiconductor or die or chip or IC) and (adhesive or under near fill\$3) and lead ) and die pad	USPAT	2004/02/19 15:14
3	BRS	785	((semiconductor or die or chip or IC) and (adhesive or under near fill\$3) and lead ) and "die pad"	USPAT	2004/02/19 15:14
4	BRS	1	5969461.pn.	USPAT	2004/02/19 20:21
5	BRS	407	257/666 and (flip or "face down") and ("underfill" or adhesive or glue)	USPAT	2004/02/19 20:25
6	BRS	71	257/666 and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT	2004/02/19 20:32
7	BRS	50	257/676 and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT	2004/02/19 20:32
8	BRS	7	257/666 and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/19 20:32
9	BRS	52	257/676 and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02/19 20:35

	Type	Hits	Search Text	DBs	Time Stamp
10	BRS	61	(257/678 or 257/688 or 257/711) and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 20:40
11	BRS	84	(257/731 or 257/732 or 257/733 or 257/778) and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 20:49
12	BRS	1	"4763188".PN.	USPAT	2004/02 /19 20:44
13	BRS	1	"5012323".PN.	USPAT	2004/02 /19 20:44
14	BRS	1	"5025306".PN.	USPAT	2004/02 /19 20:44
15	BRS	1	"5291061".PN.	USPAT	2004/02 /19 20:44
16	BRS	1	"5323060".PN.	USPAT	2004/02 /19 20:44
17	BRS	74	(257/782 or 257/783 or 257/684 or 257/690) and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 20:51

	Type	Hits	Search Text	DBs	Time Stamp
18	BRS	103	(257/692 or 257/737 or 257/767 or 257/779 or 257/795) and (flip or "face down") and ("underfill" or adhesive or glue) and "die pad"	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 20:53
19	BRS	134	(semiconductor or chip or die or IC) and (flip ) and ("underfill" ) and ("die pad" or mount\$ near structure) and lead	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:04
20	BRS	1	"3871015".PN.	USPAT	2004/02 /19 21:00
21	BRS	1	"5400950".PN.	USPAT	2004/02 /19 21:00
22	BRS	1	"5448114".PN.	USPAT	2004/02 /19 21:00
23	BRS	1	"6121062".PN.	USPAT	2004/02 /19 21:00
24	BRS	1	"6113728".PN.	USPAT	2004/02 /19 21:00
25	BRS	1	"6111322".PN.	USPAT	2004/02 /19 21:01
26	BRS	1	"5804882".PN.	USPAT	2004/02 /19 21:03
27	BRS	1	"5686763".PN.	USPAT	2004/02 /19 21:03
28	BRS	1	"5677575".PN.	USPAT	2004/02 /19 21:03
29	BRS	1	"RE35119".PN.	USPAT	2004/02 /19 21:03
30	BRS	1	"5448114".PN.	USPAT	2004/02 /19 21:03

	Type	Hits	Search Text	DBs	Time Stamp
31	BRS	1	"5400950".PN.	USPAT	2004/02 /19 21:04
32	BRS	1	"3871015".PN.	USPAT	2004/02 /19 21:04
33	BRS	316	(361/777 or 361/779 or 361/783) and (semiconductor or chip or die or IC) and (flip ) and ("underfill" or adhesive or glue) and lead	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:08
34	BRS	794	(438/108 or 438/118 or 438/119) and (semiconductor or chip or die or IC) and (flip ) and ("underfill" or adhesive or glue) and lead	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:09
35	BRS	196	(174/250 or 174/256 or 174/257) and (semiconductor or chip or die or IC) and (flip ) and ("underfill" or adhesive or glue) and lead	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:10
36	BRS	1016	(174/260 or 174/259 or 257/737 or 257/738) and (semiconductor or chip or die or IC) and (flip ) and ("underfill" or adhesive or glue) and lead	USPAT ; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:12

	Type	Hits	Search Text	DBs	Time Stamp
37	BRS	844	(29/832 or 29/840 or 228/180.22) and (semiconductor or chip or die or IC) and (flip) and ("underfill" or adhesive or glue) and lead	USPAT; US-PG PUB; EPO; JPO; DERWE NT; IBM_T DB	2004/02 /19 21:13